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S/N 10/845315

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chris Baldwin

Examiner: Ori Nadav

Serial No.: 10/045315

Group Art Unit: 2811

Filed: October 24, 2001

Docket No.: 884.537US1

Title: MECHANICAL SUPPORT SYSTEM FOR A THIN PACKAGE

3/27/03

Smith

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on December 18, 2002. Please amend the above-identified patent application as follows.

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IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect cancellation of claim 14 and amendment of previously pending claims 7, 15 and 17-19. The specific amendments to individual claims are detailed in the following marked up set of claims.

7. (Amended) An electronic package comprising:

an interposer having an upper surface and a lower surface, the interposer having a thickness less than 1 mm;

a die secured to the upper surface of the interposer;

a pin carrier having a cavity, the pin carrier being secured to the lower surface of the interposer such that the cavity is [against] adjacent, the interposer opposite to the die;

an electronic component secured to the lower surface of the interposer, the electronic component being positioned within the cavity in the pin carrier; [and]

the interposer being thin enough such that the interposer is incapable of withstanding a mechanical load generated by the die and the pin carrier to an identical electronic package; and

an encapsulant at least partially filling the cavity to mechanically support the interposer during mechanical loading the package.